

**AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

**LISTING OF CLAIMS**

1. (Currently Amended) A semiconductor relay system, comprising:  
an essentially cuboid housing including an attachment face and including, as connecting faces, four side surfaces arranged at right angles to the attachment face and a front face opposite the attachment face; and  
a functional module configured for load circuit monitoring; and  
at least one electrical connection element and at least one mechanical connection element, provided on a number of the connecting faces, for connection of athe functional module connectable to the housing.
2. (Currently Amended) The semiconductor relay system as claimed in claim 1, wherein the functional module is connected to two connecting faces.
3. (Cancelled)
4. (Currently Amended) The semiconductor relay system as claimed in claim 1, wherein the functional module is providedfurther configured for power control in the load circuit.

5. (Currently Amended) The semiconductor relay system as claimed in claim 1, wherein the functional module is drivable by use of an analogue signal.
6. (Currently Amended) The semiconductor relay system as claimed in claim 1, wherein the functional module is ~~provided~~further configured for current measurement.
7. (Currently Amended) The semiconductor relay system as claimed in claim 1, wherein the functional module is ~~provided~~further configured for analogue/digital signal conversion.
8. (Currently Amended) The semiconductor relay system as claimed in claim 1, wherein the functional module is connectable to the housing without the use of any tools.
9. (Currently Amended) The semiconductor relay system as claimed in claim 8, wherein the functional module is snapable onto the housing.
10. (Currently Amended) The semiconductor relay system as claimed in claim 1, wherein a plurality of functional modules are connectable to the housing.
11. (Currently Amended) The semiconductor relay system as claimed in claim 1, wherein the functional module includes a base face aligned with the attachment face of the housing.

12. (Currently Amended) The semiconductor relay system as claimed in claim 1, wherein the functional module has two attachment limbs, arranged on both sides of an opening in the housing and each aligned parallel to one side surface.

13. (Currently Amended) The semiconductor relay system as claimed in claim 2, wherein the functional module is provided-further configured for load circuit monitoring.

14. (Currently Amended) The semiconductor relay system as claimed in claim 2, wherein the functional module is provided-further configured for power control in the load circuit.